

IN THE CLAIMS

1. (currently amended) A semiconductor chip mounting component comprising:

(a) a support structure adapted for engagement with a semiconductor chip having a top surface, a bottom surface, and a gap extending through said support structure between said surfaces for and defining first and second portions of said support structure on opposite sides of the gap;

(b) at least one elongated bus disposed alongside said gap, on said second portion of said support structure; and

(bc) a plurality of electrically conductive leads, each said lead having a connection section extending across said gap, said connection section having a first end disposed on the first portion of the support structure on one side of the gap, and a second end secured to said bus support structure on an opposite side of said gap, and a frangible section; (c) at least one elongated bus disposed alongside said gap, on one of said first and second portions of said support structure, wherein each of said leads extends across said gap and is connected to the bus and wherein, said gap being open at said bottom surface of said support structure, said leads are being adapted to be bonded to contacts on a semiconductor chip disposed beneath said bottom surface by breaking the frangible sections of said leads so as to disconnect said second ends of said leads from the bus and engage the leads with the contacts of the chip.

2. (original) The component of claim 1, wherein the gap includes a plurality of holes.

3. (original) The component of claim 2, wherein at least one of the leads extends across each of the holes.

4. (original) The component of claim 1, wherein the gap includes at least one elongated slot and wherein each of the leads extends across one of the elongated slots.

5. (original) The component of claim 4, wherein at least one of said elongated buses is disposed alongside each of said elongated slots.

6. (original) The component of claim 1, wherein the frangible sections of at least some of the leads are disposed adjacent the second ends of said leads.

7. (canceled)

8. (original) The component of claim 1, further comprising a polymeric reinforcement in contact with each said lead.

9. (original) The component of claim 1, wherein the bus is comprised of a metallic material.

10. (currently amended) The component of claim 1, wherein the support structure includes a dielectric layer, said dielectric layer including first and second portions, said first portion of said support structure including said first portion of said dielectric layer, said second portion of said support structure including said second portion of said dielectric layer.

11. (original) The component of claim 10, wherein the dielectric layer is flexible.

12. (original) The component of claim 10, wherein the support structure further includes a compliant layer.

13. (currently amended) The component of claim 11, wherein the support structure includes a said dielectric layer defining a said top surface of said support structure and said compliant layer defining said a bottom surface of said support structure.

14. (original) The component of claim 13, wherein the leads are disposed on the dielectric layer.

15. (original) The component of claim 1, wherein the connection section and the frangible section of each lead are formed integrally with one another and with the associated bus, the connection section of each lead defining a pair of opposed horizontal edges, and the frangible lead section of each lead having a pair of notches extending horizontally inwardly from said opposed edges to define a neck having a width less than the width between said edges.

16. (original) The component of claim 15, wherein each said lead has a second end securement section extending between the frangible section and the associated bus.

17. (currently amended) A component as claimed in claim 1, wherein said support structure includes the first and second portions, gap includes ing a plurality of elongated slots extending substantially around said first portion so that the slots are disposed between the first portion and the second portion, the component including a plurality of said elongated buses arranged on said second portion so that one such bus extends alongside each said slot.

18. (previously amended) The component as claimed in claim 17, wherein said buses are connected to one another so that said buses cooperatively form a structure on said second portion substantially surrounding said first portion and said slots.

19. (currently amended) The component as claimed in claim 18, wherein said slots are connected to one another to form a substantially continuous channel surrounding said first portion, said first portion being connected to said second portion only through said leads, whereby said first portion will be detached from said second portion upon breakage of said frangible sections.

20. (currently amended) The component of claim 1, wherein said first and second portions of said support structure comprises a unitary support.

21. (previously added) The component of claim 20, wherein said unitary support comprises a layer of dielectric material.

22. (previously added) The component of claim 1, wherein said frangible section is mechanically weaker than said first and second ends of said connection section, whereby said frangible section is disconnectable from one of said first and second ends upon application of a force to said connection section.

23. (previously added) The component of claim 22, wherein said frangible section is disposed overlying said gap between said first and second ends.

24. (previously added) The component of claim 1, wherein said frangible section is disposed overlying said gap between said first and second ends.

25. (currently amended) The component of claim 1, wherein said first and second ends of said connection section are joined together by said frangible sections overlying overlie said gap, at least one of said first and second ends of each said connection section is displaceable within said gap relative to said support structure upon severing said frangible section while leaving a remainder of said connection section intact.

26. (new) The component of claim 1 further comprising terminals disposed on said first portion of support structure, at least some of said leads having their first ends connected to said terminals.

27. (new) A semiconductor chip mounting component comprising:

(a) a support structure adapted for engagement with a semiconductor chip having a top surface, a bottom surface, and a gap extending through said support structure between said surfaces and defining first and second portions of said support structure on opposite sides of said gap;

(b) a plurality of electrically conductive leads, each said lead having a connection section extending across said gap, said connection section having a first end disposed on the first portion of the support structure, a second end secured to said bus, and a frangible section,

wherein said frangible section is disconnectable from one side of said first and second ends upon application of a force to said connection section;

(c) said gap being open at said bottom surface of said support structure, said leads being adapted to be bonded to contacts on a semiconductor chip disposed beneath said bottom surface by breaking the frangible section of said leads so as to disconnect said second ends of said leads from said bus and engage said leads with the contacts of the chips, said frangible section is mechanically weaker than said first and second ends of said connection section;

(d) terminals disposed on said first portion of support structure, wherein at least some of said leads having their first ends connected to said terminals.